

# Editorial

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Welcome to Volume 1, Number 4 of IMAPS' Journal of Microelectronics and Electronic Packaging.

This is the fourth quarterly issue that I have refereed as its Editor-in-Chief. "Time goes by fast when you are having fun!"

One of the many great characteristics of IMAPS is the wide spectrum of technologies that it encompasses. This issue covers transfer molding, laser processing, RF IC processing, high temperature components, power microelectronics, BGA and CSP packages, and thermal analysis. Wow!

I am pleased to announce the addition of Mr. Phillip J. Zulueta to our Journal Advisory Board. He will soon be the "First Past President" of IMAPS and has considerable resources to draw on for reviewing the papers that are submitted for publication in our Journal.

Wishing all our readers "Happy Holidays".

Regards,  
Delip "Doug" Bokil  
Editor-in-Chief